

SSC8068GN4

N-Channel Enhancement Mode MOSFET

Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	l _D
60V	+20V	24mΩ@10V 25A	25∆
000	<u> </u>	28mΩ@4V5	23/4

> Description

This SSC8068GN4 uses advanced trench technology to provide excellent RDSON and low gate charge. The complementary MOSFETS may be used to form a level shifted high side switch, and for a host of other applications.

100% UIS + ΔVDS + Rg Tested!

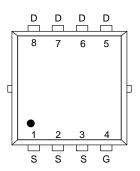
Applications

- Load Switch
- PWM Application
- Power Management
- Motor Driving in Power Tool, E-vehicle, Robotics

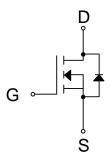
Ordering Information

Device	Package	Shipping
SSC8068GN4	PDFN3.3X3.3-8L	5000/Reel

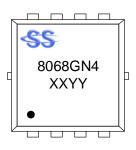
Pin configuration



PDFN3.3X3.3-8L (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)



➤ Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit		
V _{DSS}	Drain-to-Source Volta	Drain-to-Source Voltage		V	
V _{GSS}	Gate-to-Source Volta	ige	±20	V	
		T _C =25℃	25	Δ.	
l _D	Continuous Drain Current ^d	T _C =100°C	14	Α	
	Continuous Brain Comment 2	T _A =25℃	9	Δ.	
IDSM	Continuous Drain Current ^a	T _A =70°C	6	- A	
I _{DM}	Pulsed Drain Curren	Pulsed Drain Current b		Α	
Б	Davis Dissipation 6	Tc=25°C	27.8	10/	
P _D	Power Dissipation ^c	T _C =100°C	11.1	W	
Б	Davis Dissipation 2	T _A =25℃	3.13	10/	
P _{DSM}	Power Dissipation ^a	T _A =70°C	2	W	
I _{AS}	Avalanche Current b L=0.5mH Single Pulse		10	Α	
Eas	Avalanche Energy ^b L=0.5mH Single Pulse		25	mJ	
TJ	Operation junction temperature		-55~150	°C	
T _{STG}	Storage temperature range		-55~150	$^{\circ}$	

➤ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance a	40	°C ///
R ₀ JC	Junction-to-Case Thermal Resistance	4.5	°C/W

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25°C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

SSC-V1.0 www.sscsemi.com Analog Future



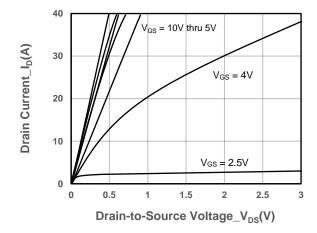


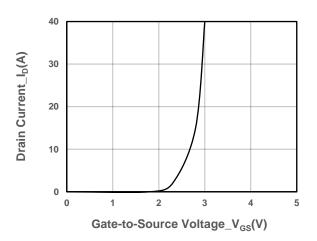
\succ Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250uA$	1	1.5	2.5	V
Drain Course On Registeres	R _{DS(on)}	V _{GS} = 10V, I _D = 6A		24	30	0
Drain-Source On-Resistance		V _{GS} = 4.5V, I _D = 3A		28	40	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	Igss	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Transconductance	G _{FS}	$V_{DS} = 5V$, $I_D = 5A$		10		s
Forward Voltage	V _{SD}	V _G S = 0V, I _S = 5A		0.8	1.3	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		1.3		Ω
Input Capacitance	Ciss	V 50V V 0V		1400		pF
Output Capacitance	Coss	V _{DS} = 50V, V _{GS} = 0V,		70		
Reverse Transfer Capacitance	Crss	f = 1MHz		58		
Total Gate Charge	Q _G	V 40V V 20V		6		
Gate to Source Charge	Q _{GS}	V _{GS} = 10V, V _{DS} = 30V,		1.6		nC
Gate to Drain Charge	Q _{GD}	- I _D = 5A		1.3		
Turn-on Delay Time	T _{D(ON)}			8		
Rise Time	Tr	V _{GS} = 10V, V _{DS} = 10V,		58		
Turn-off Delay Time	T _{D(OFF)}	$R_L = 6\Omega$, $R_G = 6\Omega$		20		ns
Fall Time	T _f			88		
Diode Recovery Time	Trr	I _F =5A, di/dt=500A/us		12		ns
Diode Recovery Charge	Q _{rr}	I _F =5A, di/dt=500A/us		15		nC



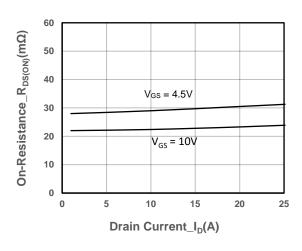
➤ Typical Performance Characteristics (T_A=25°C unless otherwise noted)

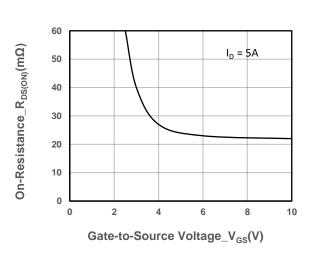




Output Characteristics

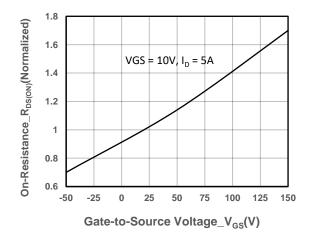
Transfer Characteristics

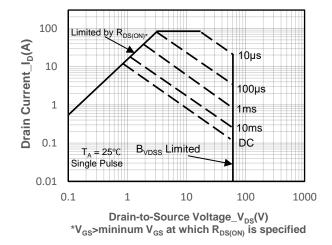




On-Resistance vs. Drain Current and Gate Voltag

On-Resistance vs. Gate-to-Source Voltage



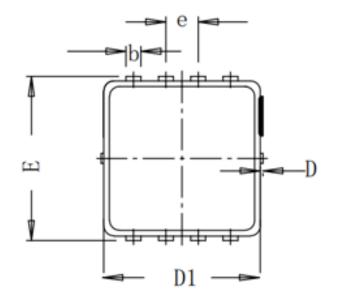


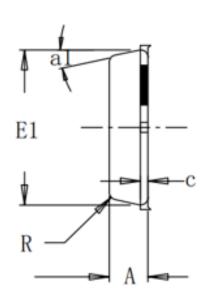
On-Resistance vs. Junction Temperature

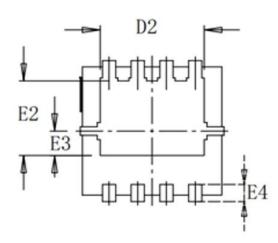
Safe Operating Area vs. Junction-to-Ambient



> Package Information







Cumbal	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
Α	0.75	0.78	0.81	
b	0.297	0.3	0.35	
С	-	0.152	-	
D	0	0.05	0.1	
D1	3.12	3.15	3.18	
D2	-	2.35	-	
Е	3.2	3.3	3.4	
E1	3.09	3.12	3.15	
E2	-	1.75	-	
E3	-	0.575	-	
E4	-	0.4	-	
R	-	0.15	-	
е	0.65BSC			
a1°	-	12°	-	



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